

USB 3.1 TYPE-C



SPECIFICATION

MATERIAL

See drawing

STANDARD DATA

Rating current:

5.0A for VBUS (i.e.,pins

A4,A9,B4,B9)

1.25A for Vconn and GND (i.e.,pins

B5,A1,A12,B1,B12)

0.25A for all the other contacts.

Operating temperature: -10°C ~

+60°C

Storage temperature: -20°C ~

+85°C

ELECTRICAL

Insulator resistance: 100Mohms

Min.

Withstanding voltage: 100 VAC / minute

Contact resistance: initial

40mohms Max;

after 50mohms Max.

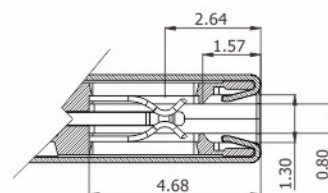
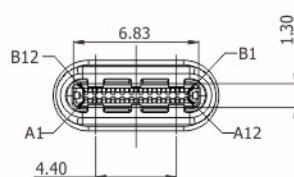
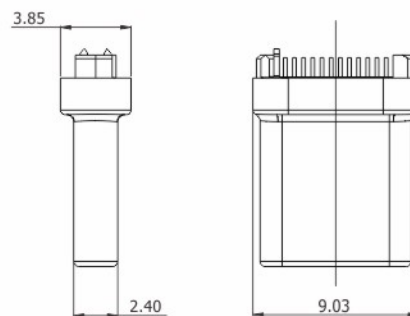
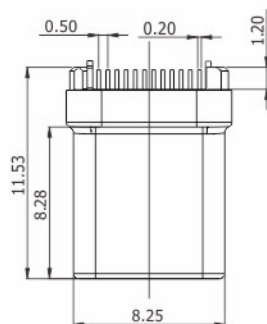
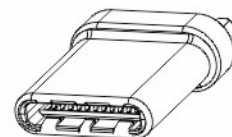
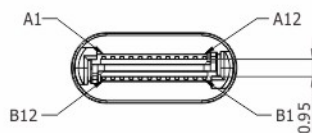
MECHANICAL

Mating force: 5 ~ 20N

Unmating force: 8 ~ 20N

Durability: 10000 cycles Min.

PART NO.



Ordering Information

Product Test ID: 5200000280

184j - $\frac{XX}{a}$ $\frac{X}{b}$ $\frac{X}{c}$ $\frac{X}{d}$ $\frac{X}{e}$ $\frac{X}{f}$

a. No. Of Pins
24: 24 positions

b. Contact Type
1: Male

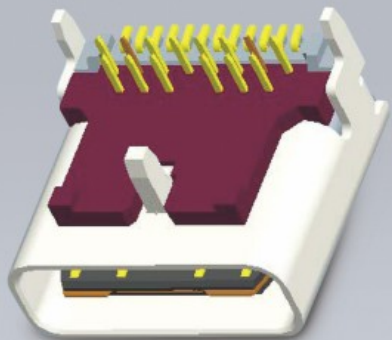
c. Contact Plating
0: Gold flash selective gold
1: 5μ" selective gold over 50μ" nickel
2: 15μ" selective gold over 50μ" nickel
3: 30μ" selective gold over 50μ" nickel

d. Shell Type
1: Nickel

e. Insulator Color
1: Black (LCP)

f. Contact Type(Signal Pin)
2: Edge Type

USB 3.1 TYPE-C WAVELESS TYPE



NOTE:

1.MATERIAL:

PLASTIC:Glass-Filled Thermoplastic
high temperature LCP G/F 30%
color:BLACK

SHELL: SUS 304

PLATE: SUS 304

MID-PLATE: SUS 304

CONTACT: Phosphor Bronze

2.PLITING:

CONTACT: 30μ" GOLD PLATING ON
CONTACT AREA

120μ" Tin PLATING ON TAIL AREA
50μ" NICKEL UNDERPLATING OVER

ALL

SHELL: 80μ" MIN Nickel

PLATE: 80μ" MIN Nickel

MID-PLATE: 120μ" MATTE-Tin VOER

50μ" NICKEL

3.ELECTRICAL

Rating current: 5.0A for VBUS (i.e.,pins
A4,A9,B4,B9)

1.25A for Vconn and GND (i.e.,pins
B5,A1,A12,B1,B12)

0.25A for all the other contacts

Insulator resistance: 100M ohms Min

Withstanding voltage: 100 VAC / minute

Contact resistance: 40 m ohms Max

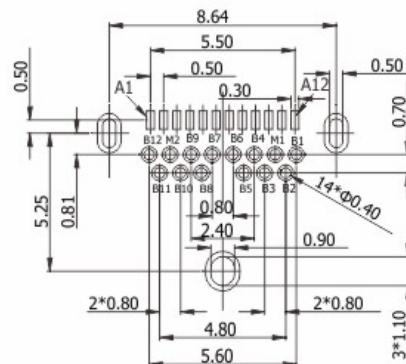
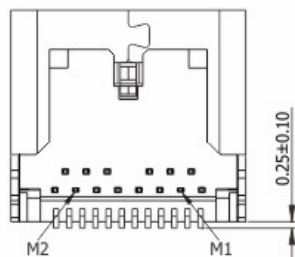
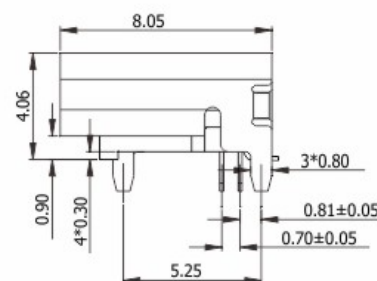
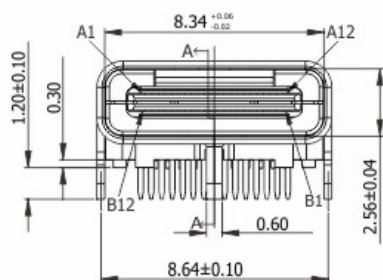
MECHANICAL

Mating force: 5 ~ 20N.

Unmating force: 8 ~ 20N.

Durability: 10000 cycles Min.

TEMPERATURE RATING:-55°C ~ +105°C



RECOMMENDED P.C.B LAYOUT T=0.6±0.05MM

Ordering Information

184j - XX X X X X X
a b c d e f

a. No. Of Pins
24: 24 positions

b. Contact Type
2: Female

c. Contact Plating
0: Gold flash selective gold
1: 5μ" selective gold over 50μ" nickel
2: 15μ" selective gold over 50μ" nickel
3: 30μ" selective gold over 50μ" nickel

d. Shell Type
1: Nickel

e. Insulator Color
1: Black (LCP)

f.Contact Type(Signal Pin)
3: Waveless Type

USB 3.1 TYPE-C SMT TWO-ROW TYPE



NOTE:

1.MATERIAL:

PLASTIC: Glass-Filled Thermoplastic
high temperature LCP G/F 30%

color: BLACK

SHELL: SUS 304

PLATE: SUS 304

MID-PLATE: SUS 304

CONTACT: Phosphor Bronze

2.PLITTING:

CONTACT: 30μ" GOLD PLATING ON
CONTACT AREA

0.5μ" GOLD PLATING ON TAIL AREA

50μ" NICKEL UNDERPLATING OVER ALL

SHELL: 80μ" MIN Nickel

PLATE: 80μ" MIN Nickel

MID-PLATE: 120μ" MATTE-Tin VOER

50μ" NICKEL

3.ELECTRICAL

Rating current: 5.0A for VBUS (i.e.,pins
A4,A9,B4,B9)

1.25A for Vconn and GND (i.e.,pins
B5,A1,A12,B1,B12)

0.25A for all the other contacts

Insulator resistance: 100M ohms Min
Withstanding voltage: 100 VAC /
minute

Contact resistance: 40 m ohms Max

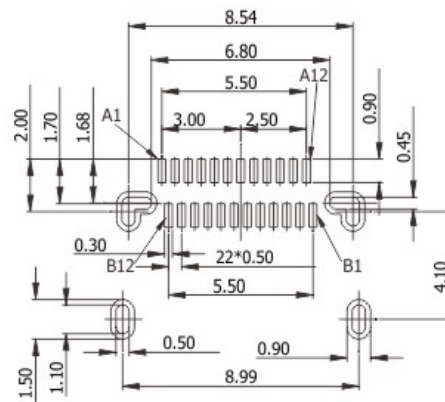
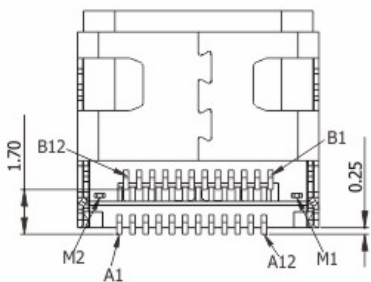
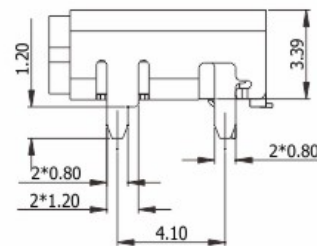
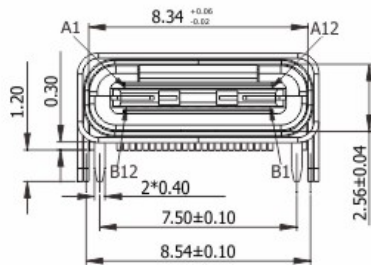
MECHANICAL

Mating force: 5 ~ 20N.

Unmating force: 8 ~ 20N.

Durability: 10000 cycles Min.

TEMPERATURE RATING:-55°C ~
+105°C



Ordering Information

184j - XX X X X X X
 a b c d e f

a. No. Of Pins
24: 24 positions

b. Contact Type
2: Female

c. Contact Plating
0: Gold flash selective gold
1: 5μ" selective gold over 50μ" nickel
2: 15μ" selective gold over 50μ" nickel
3: 30μ" selective gold over 50μ" nickel

d. Shell Type
1: Nickel

e. Insulator Color
1: Black (LCP)

f. Contact Type(Signal Pin)
4: SMT Type (Two-Row Type)